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(12) **United States Design Patent**
Juco

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(54) **SEMICONDUCTOR WAFER PROCESSING TOOL**

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(73) Assignee: **Lam Research Corporation**, Fremont, CA (US)

(**) Term: **15 Years**

(21) Appl. No.: **29/690,193**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**; D10/46

(58) **Field of Classification Search**
USPC D3/30, 200, 201, 212, 217, 283, D3/308–310, 326; D8/349; D9/414, 430, D9/456, 499; D10/46, 75, 77, 78, 81, D10/102; D13/182; D15/140
CPC H01L 21/561; H01L 21/78; H01L 24/11; H01L 24/96; H01L 24/97
See application file for complete search history.

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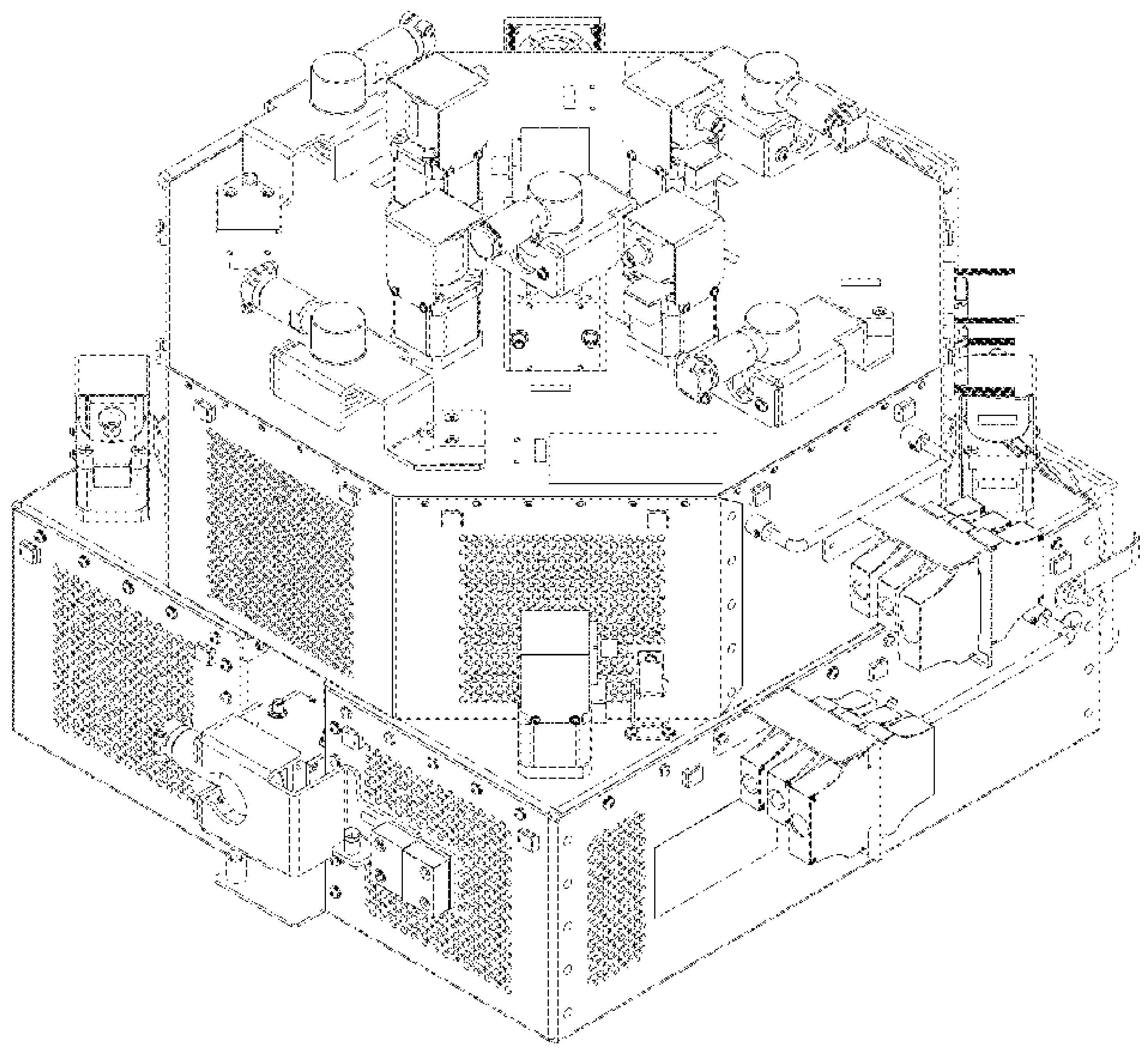
(57) **CLAIM**

The ornamental design for a semiconductor wafer processing tool, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a semiconductor wafer processing tool, showing my new design;
FIG. **2** is a front view thereof;
FIG. **3** is a rear view thereof;
FIG. **4** is a left side view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a top plan view thereof; and,
FIG. **7** is a bottom plan view thereof.

1 Claim, 7 Drawing Sheets



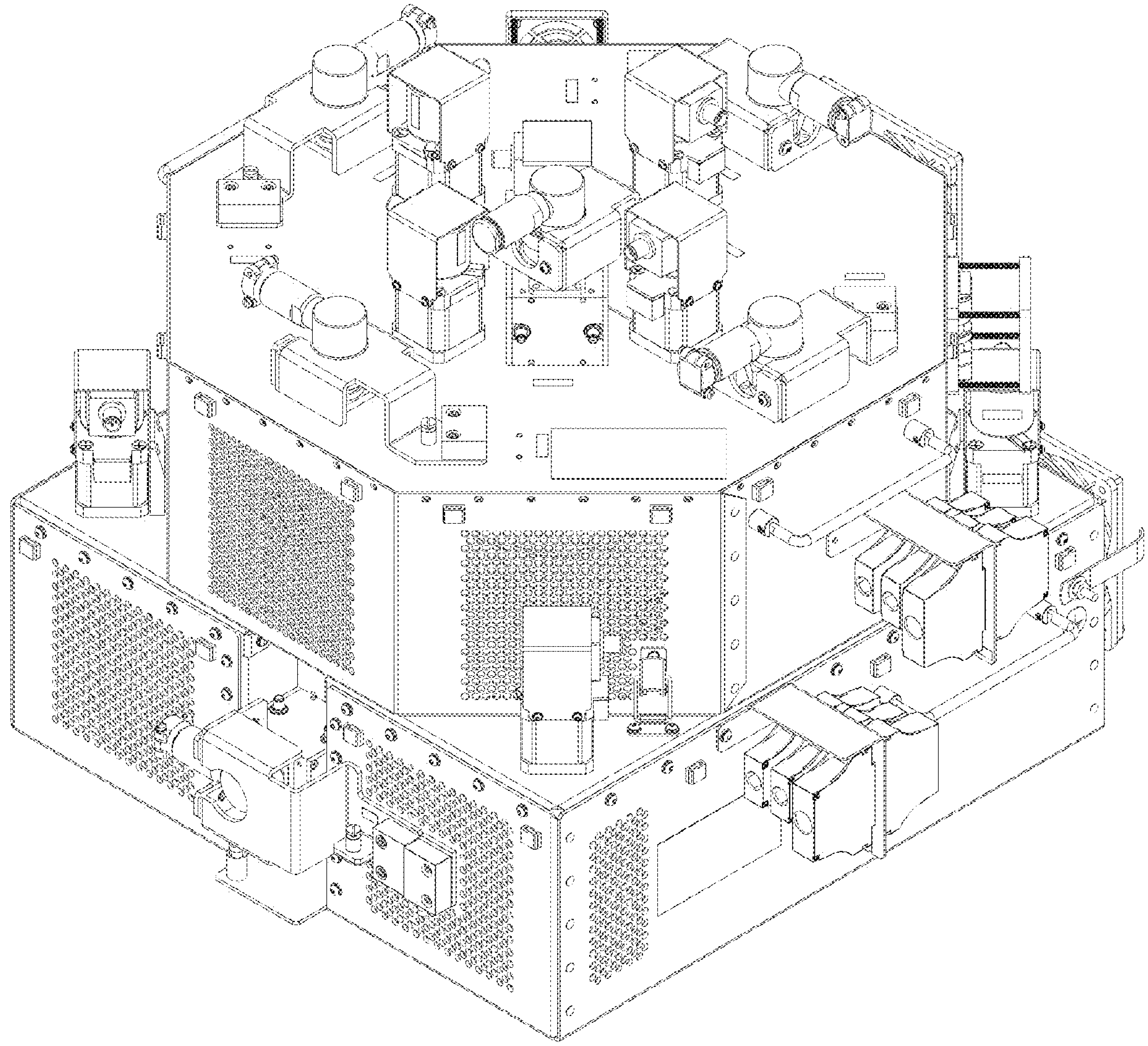


FIG. 1

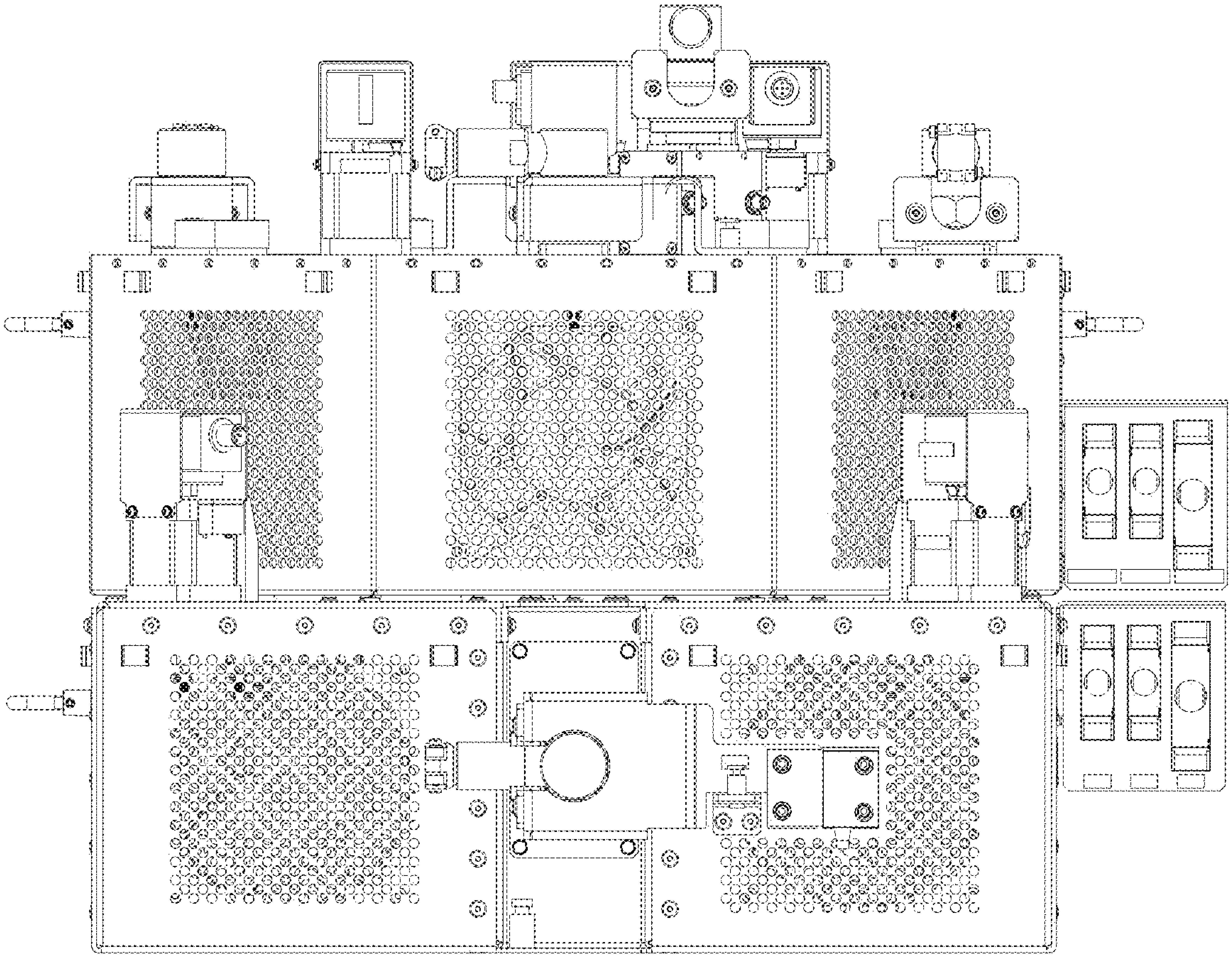


FIG. 2

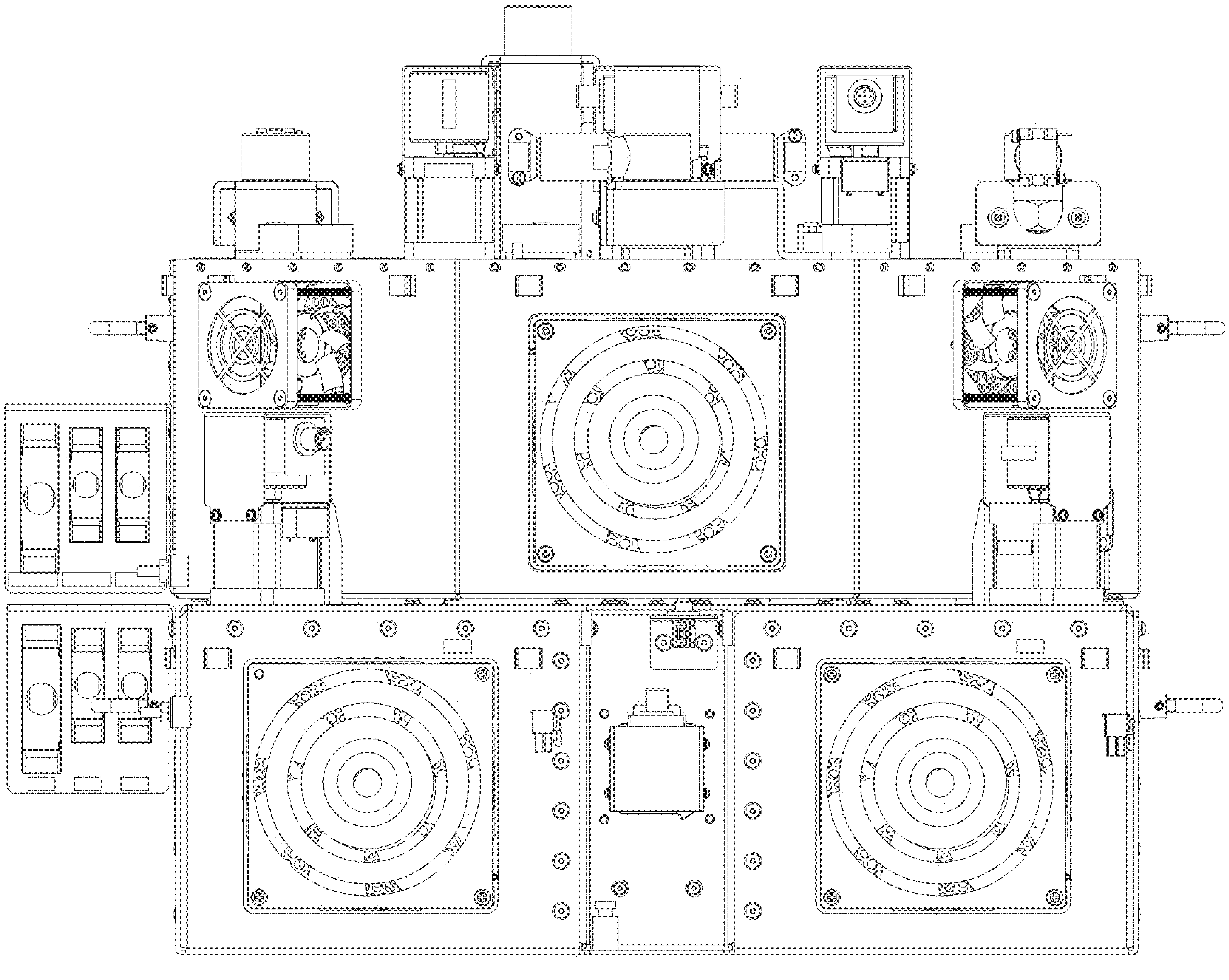


FIG. 3

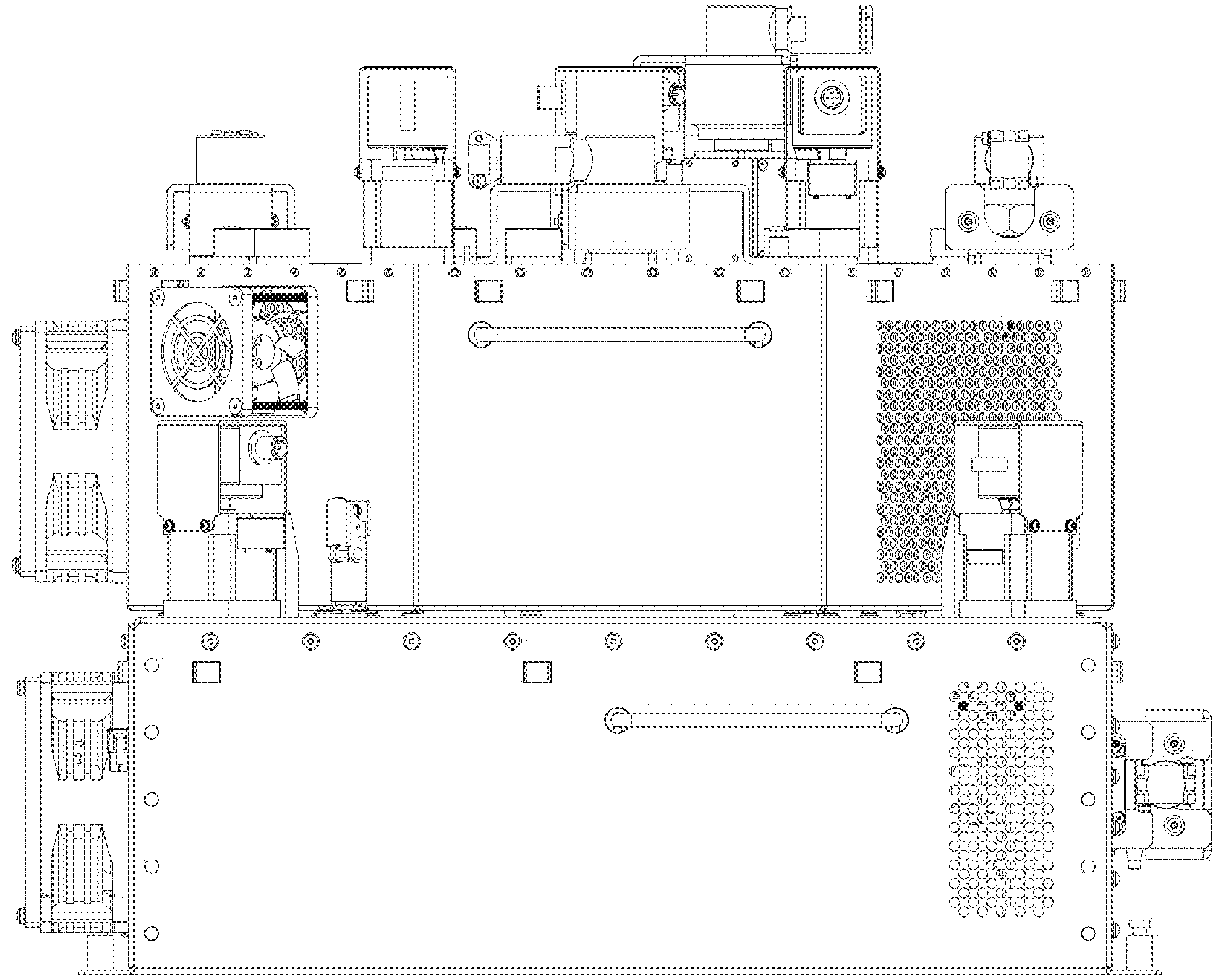


FIG. 4

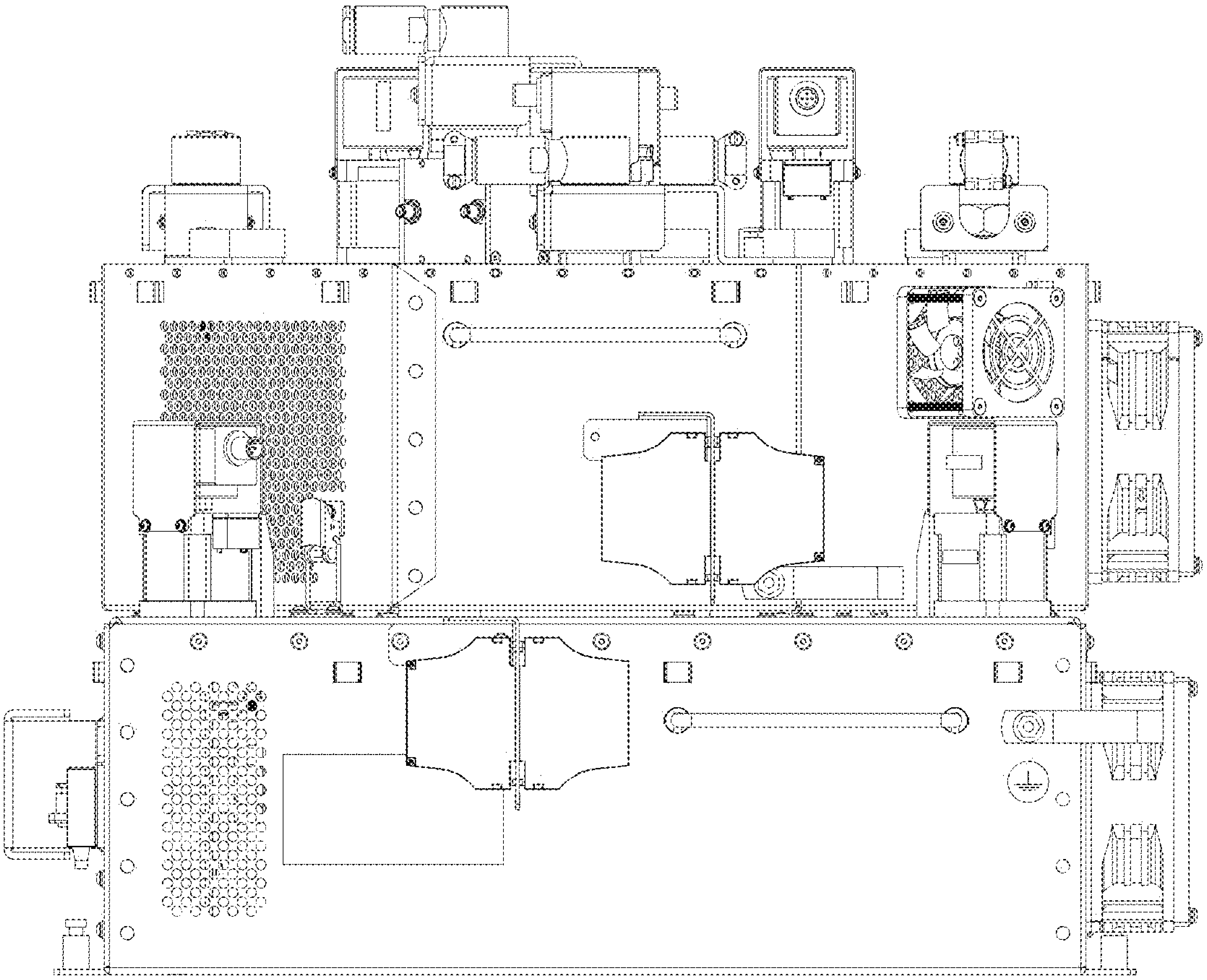


FIG. 5

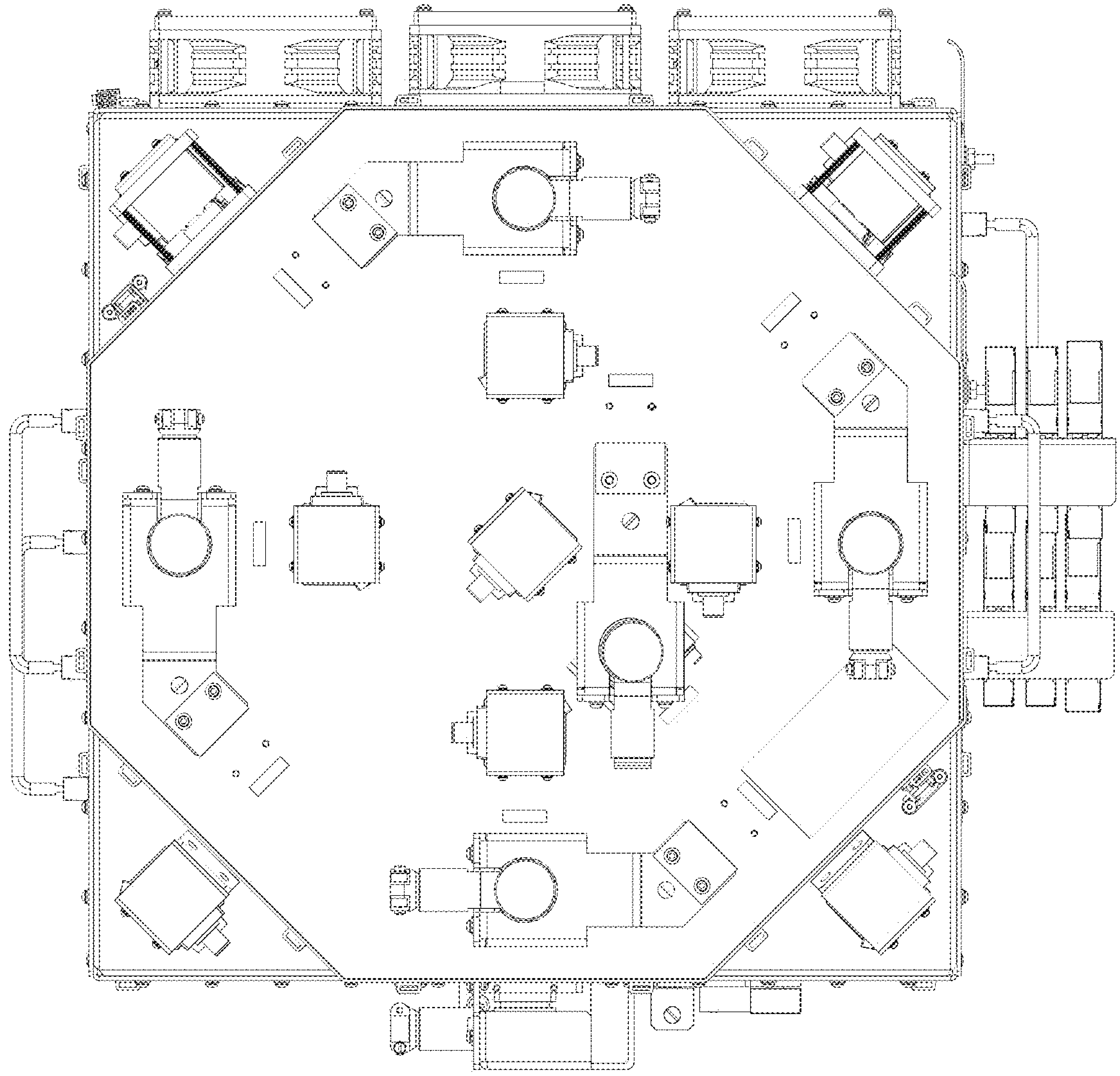


FIG. 6

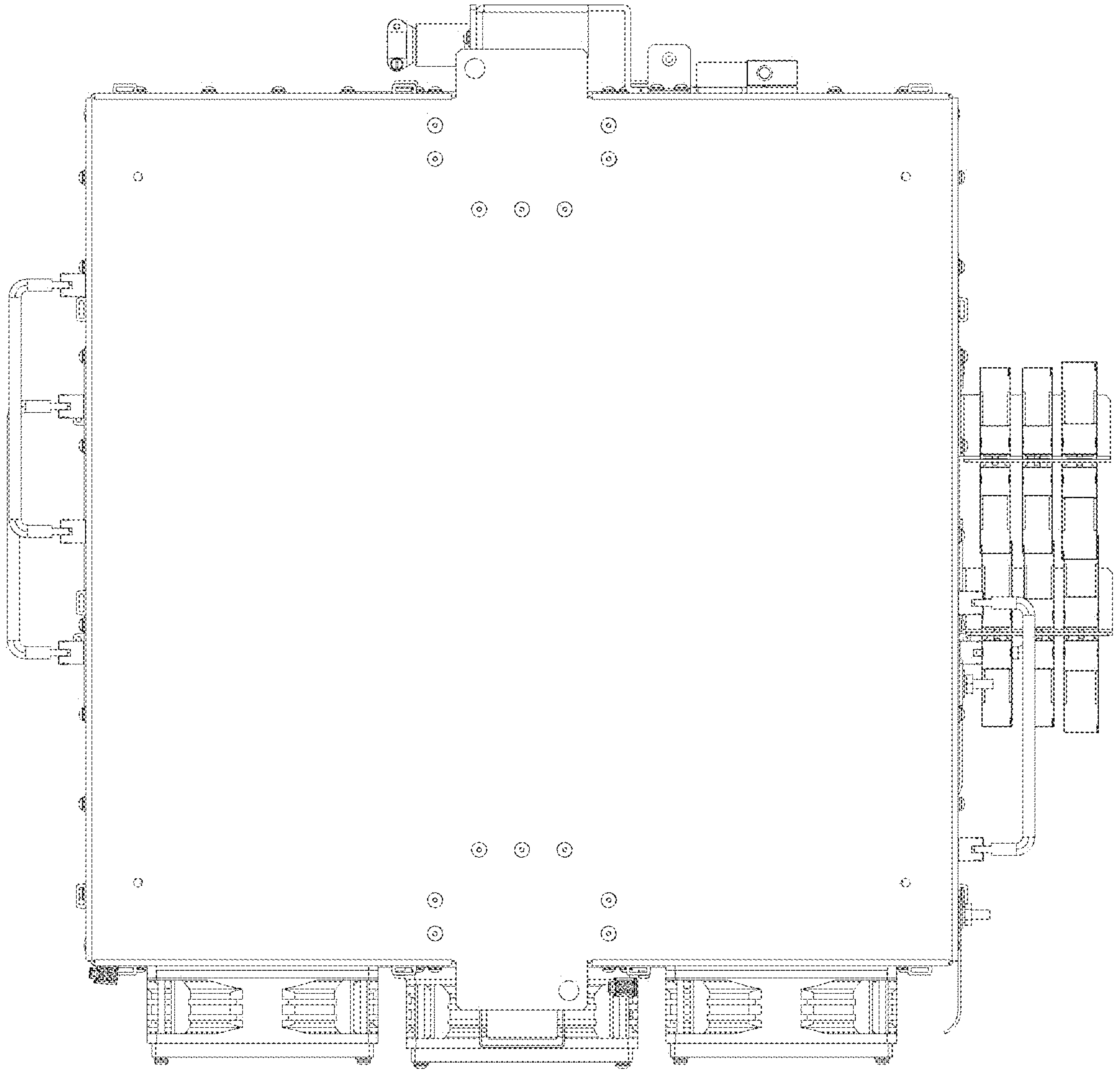


FIG. 7